TEXAS INSTRUMENTS

Bill of Materials

TI DESIGNS
TIDA-00002-HEATEVM
SLVU468C

QUANTITY	DESIGNATOR	DESCRIPTION	MANUFACTURER	PART NUMBER
3	C519, C520, C521	Capacitors, C0G, 50V, 5%	Kemet	C0402H102J5GACTU
5	C522, C523, C524, C525, C526	Capacitors, C0G, 50V, 5%	Kemet	C0402H101J5GACTU
3	C17, C24, C32	Capacitors, C0G, 25V, 5%	Kemet	C0805H333J3GACTU
45	C1, C8, C9, C10, C12, C13, C14, C16, C18, C20, C21, C22, C23, C25, C26, C28, C29, C30, C31, C33, C34, C35, C37, C39, C40, C43, C44, C50, C51, C52, C53, C54, C500, C501, C502, C508, C509, C510, C512, C514, C518, C533, C534, C535, C536	Capacitors, C0G, 25V, 5%	Kemet	C1206H104J3GACTU
8	C11, C45, C48, C56, C57, C58, C504, C511	Capacitors, C0G, 50V, 5%	Kemet	C1206H103J5GACTU
6	C503, C505, C506, C507, C513, C517	Capacitors, C0G, 50V, 5%	Kemet	C1812H224J5GACTU
6	C2, C3, C4, C7, C15, C42	Capacitors, 60V, hybrid	Evans	HCB100680HT
1	C27	Capacitors, 50V, 10%	Avx Corporation	SMX55C105KAN240
1	C62	Capacitors, 25V, 10%	Avx Corporation	SMX43C106KAN360
5	C527, C528, C530, C531, C532	Capacitors, 25V, 10%	Avx Corporation	SMX43C106KAN360
10	R1, R2, R7, R8, R9, R10, R11, R12, R60, R61	Resistors, 12.5mW, 0.1%, 25ppm/C	Vishay Sfernice	PHT0603Y1002BGT200
3	R6, R24, R14	Resistors, 20mW, 0.1%, 25ppm/C	Vishay Sfernice	PHT0805Y1001BGT200
7	R15, R31, R35, R49, R50, R501, R502	Resistors, 20mW, 0.5%, 25ppm/C	Vishay Sfernice	PHT0805E10R0DGT200
28	R3, R4, R5, R30, R38, R39, R40, R44, R46, R62, R63, R64, R65, R66, R67, R69, R72, R73, R74, R92, R94, R97, R500, R37, R47, R48, R51, R52	Resistors, 0.25W, 0.02%, 5ppm/C	Vishay Sfernice	PLTT0805Z1002QGT5
9	R78, R79, R45, R53, R55, R57, R58, R59, R42	Resistors, 20mW, 0.1%, 25ppm/C	Vishay Sfernice	PHT0805Y1000BGT200
6	R19, R20, R13, R29, R34, R25	Resistors, 20mW, 0.1%, 25ppm/C	Vishay Sfernice	PHT0805Y1003BGT200
9	R70, R71, R81, R83, R84, R85, R98, R99, R26	Resistors, 0.25W, 0.02%, 5ppm/C	Vishay Thin Film	PLTT0805Z2522QGT5
4	R18, R21, R54, R56	Resistors, 0.25W, 0.02%, 5ppm/C	Vishay Thin Film	PLTT0805Z5002QGT5
1	RTD	Sensor, Transducers	Susumu	PPG102C1RD
2	U16, U17	Integrated Circuits	Texas Instruments	SN65HVD233SHKJ
1	U12	Integrated Circuits	Texas Instruments	INA333SHKJ
5	U1, U2, U3, U9, U10	Integrated Circuits	Texas Instruments	OPA211SHKJ
3	U5, U7, U11	Integrated Circuits	Texas Instruments	OPA2333SHKJ
1	U6	Integrated Circuits	Texas Instruments	REF5025SHKJ
1	U15	Integrated Circuits	Texas Instruments	SN65HVD11SHKJ
3	U8, U13, U14	Integrated Circuits	Texas Instruments	THS4521SHKJ
1	U4	Integrated Circuits	Texas Instruments	ADS1278SHFQ
1	U19	Integrated Circuits	Texas Instruments	SM470R1B1MHFQS
6	JP1, JP5, JP17, JP22, JP23, JP500	Connectors, 0.1", 1x3	Samtec	HTSW-103-08-G-S
6	JP6, JP9, JP13, JP18, JP21, JP502	Connectors, 0.1", 1x2	Samtec	HTSW-102-08-G-S
1	JP2	Connectors, 0.1", 1x12	Samtec	HTSW-112-08-G-S
2	JP3, JP26	Connectors, 0.1", 1x10	Samtec	HTSW-110-08-G-S
2	JP4, JP8	Connectors, 0.1", 1x4	Samtec	HTSW-104-08-G-S
3	JP7, JP14, JP15	Connectors, 0.1", 1x8	Samtec	HTSW-108-08-G-S
1	JP10	Connectors, 0.1x0.1", 2x3	Samtec	HTSW-103-08-G-D

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1	JP11	Connectors, 0.1x0.1", 2x2	Samtec	HTSW-102-08-G-D
1	JP12	Connectors, 0.1x0.1", 2x8	Samtec	HTSW-108-08-G-D
1	JP16	Connectors, 0.1x0.1", 2x6	Samtec	HTSW-106-08-G-D
1	JP19	Connectors, 0.1x0.1", 2x7	Samtec	HTSW-107-08-G-D
1	JP20	Connectors, 0.1x0.1", 2x10	Samtec	HTSW-110-08-G-D
1	JP27	Connectors, 0.1x0.1", 2x5	Samtec	HTSW-105-08-G-D
1	OSC1	Crystals, 200C, 3.3V	Frequency Management Inte	5890056-7M50
10	SCREWS	4-40 Phillips, 0.25" - SS	Building Fasteners	PMSSS 440 0025 PH
10	STANDOFFS	4-40 Round - F/F, 0.75" - ALUM	Keystone Electronics	2029
12	TP1, TP2, TP3, TP4, TP5, TP6, TP7, TP8, TP9, TP10, TP11, TP12	Test Equipment	Keystone Electronics	5016
0	C5	Undefined Category	DNI	DNI
0	R16, R17, R27, R32, R28, R33, R68, R93, R95, R96, R503	Undefined Category	DNI	DNI
0	SB1, SB2, SB3, SB4, SB5, SB6, SB7, SB8, SB9, SB10,	Undefined Category	DNI	DNI
0	U18	Undefined Category	DNI	DNI

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